ON Semiconductor®

FDS8958B

Dual N & P-Channel PowerTrench® MOSFET
Q1-N-Channel: 30 V, 6.4 A, 26 mΩ Q2-P-Channel: -30 V, -4.5 A, 51 mΩ

Features

Q1: N-Channel

- Max $r_{DS(on)}$ = 26 mΩ at V_{GS} = 10 V, I_D = 6.4 A
- Max $r_{DS(on)}$ = 39 mΩ at V_{GS} = 4.5 V, I_D = 5.2 A

Q2: P-Channel

- Max $r_{DS(on)}$ = 51 mΩ at V_{GS} = -10 V, I_D = -4.5 A
- Max $r_{DS(on)}$ = 80 mΩ at V_{GS} = -4.5 V, I_D = -3.3 A
- HBM ESD protection level > 3.5 kV (Note 3)
- RoHS Compliant

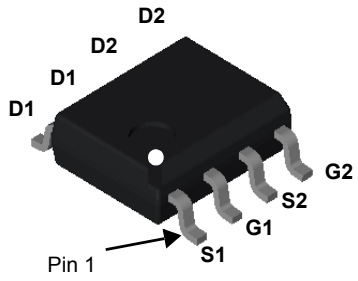
General Description

These dual N- and P-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's advanced PowerTrench® process th at has been especially tailored to minimize on-state resistan ce and yet maintain superior switching performance.

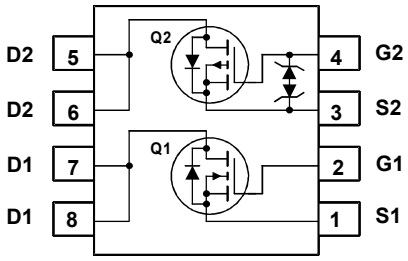
These devices are well suite d for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Application

- DC-DC Conversion
- BLU and motor drive inverter



SO-8



MOSFET Maximum Ratings T_C = 25 °C unless otherwise noted

Symbol	Parameter			Q1	Q2	Units
V_{DS}	Drain to Source Voltage			30	-30	V
V_{GS}	Gate to Source Voltage			±20	±25	V
I_D	Drain Current - Continuous	T_A = 25 °C		6.4	-4.5	A
	- Pulsed			30	-30	
P_D	Power Dissipation for Dual Operation			2.0		W
	Power Dissipation for Single Operation	T_A = 25 °C	(Note 1a)	1.6		
		T_A = 25 °C	(Note 1b)	0.9		
E_{AS}	Single Pulse Avalanche Energy		(Note 4)	18	5	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range			-55 to +150		°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8958B	FDS8958B	SO-8	13 ”	12 mm	2500 units

October-2017,Rev.3

Publication Order Number:
FDS8958B/D

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
Off Characteristics							
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA, V_{GS} = 0 V I_D = -250 μA, V_{GS} = 0 V	Q1 Q2	30 -30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C I_D = -250 μA, referenced to 25 °C	Q1 Q2		24 -21		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 24 V, V_{GS} = 0 V V_{DS} = -24 V, V_{GS} = 0 V	Q1 Q2			1 -1	μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0 V V_{GS} = ±25 V, V_{DS} = 0 V	Q1 Q2			±100 ±10	nA μA
On Characteristics							
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA V_{GS} = V_{DS}, I_D = -250 μA	Q1 Q2	1.0 -1.0	2.0 -1.9	3.0 -3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C I_D = -250 μA, referenced to 25 °C	Q1 Q2		-6 5		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 6.4 A V_{GS} = 4.5 V, I_D = 5.2 A V_{GS} = 10 V, I_D = 6.4A, T_J = 125 °C	Q1		21 29 31	26 39 39	mΩ
		V_{GS} = -10 V, I_D = -4.5 A V_{GS} = -4.5 V, I_D = -3.3 A V_{GS} = -10 V, I_D = -4.5 A, T_J = 125 °C	Q2		38 60 53	51 80 72	
g_{FS}	Forward Transconductance	V_{DD} = 5 V, I_D = 6.4 A V_{DD} = -5 V, I_D = -4.5 A	Q1 Q2		20 10		S
Dynamic Characteristics							
C_{iss}	Input Capacitance	Q1 V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHZ Q2 V_{DS} = -15 V, V_{GS} = 0 V, f = 1 MHZ	Q1 Q2		405 570	540 760	pF
C_{oss}	Output Capacitance		Q1 Q2		75 115	100 155	pF
C_{rss}	Reverse Transfer Capacitance		Q1 Q2		55 100	80 150	pF
R_g	Gate Resistance		Q1 Q2		2.4 4.4		Ω
Switching Characteristics							
$t_{d(on)}$	Turn-On Delay Time	Q1 V_{DD} = 15 V, I_D = 6.4 A, V_{GS} = 10 V, R_{GEN} = 6 Ω Q2 V_{DD} = -15 V, I_D = -4.5 A, V_{GS} = -10 V, R_{GEN} = 6 Ω	Q1 Q2		4.3 6.0	10 12	ns
t_r	Rise Time		Q1 Q2		2.0 6.0	10 12	ns
$t_{d(off)}$	Turn-Off Delay Time		Q1 Q2		12 17	22 30	ns
t_f	Fall Time		Q1 Q2		2.0 7.0	10 14	ns
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 10 V V_{GS} = -10 V Q1 V_{DD} = 15 V, I_D = 6.4 A	Q1 Q2		8.3 14	12 19	nC
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 4.5 V V_{GS} = -4.5 V	Q1 Q2		4.1 7.0	5.8 9.6	nC
Q_{gs}	Gate to Source Charge	Q2 V_{DD} = -15 V, I_D = -4.5 A	Q1 Q2		1.3 1.9		nC
Q_{gd}	Gate to Drain “Miller” Charge		Q1 Q2		1.7 3.6		nC

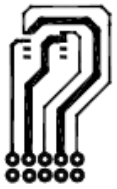
Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
Drain-Source Diode Characteristics							
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 1.3 A (Note 2) V_{GS} = 0 V, I_S = -1.3 A (Note 2)	Q1 Q2		0.8 -0.8	1.2 -1.2	V
t_{rr}	Reverse Recovery Time	Q1 I_F = 6.4 A, di/dt = 100 A/μs	Q1 Q2		17 20	30 36	ns
Q_{rr}	Reverse Recovery Charge	Q2 I_F = -4.5 A, di/dt = 100 A/μs	Q1 Q2		6 8	12 16	nC

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a) 78 °C/W when mounted on a 1 in^2 pad of 2 oz copper



b) 135 °C/W when mounted on a minimun pad

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.

3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

4. UIL condition: Starting T_J = 25 °C, L = 1 mH, I_{AS} = 6 A, V_{DD} = 27 V, V_{GS} = 10 V . (Q1)

Starting T_J = 25 °C, L = 1 mH, I_{AS} = -4 A, V_{DD} = -27 V, V_{GS} = -10 V. (Q2)

Typical Characteristics (Q1 N-Channel) T_J = 25 °C unless otherwise noted

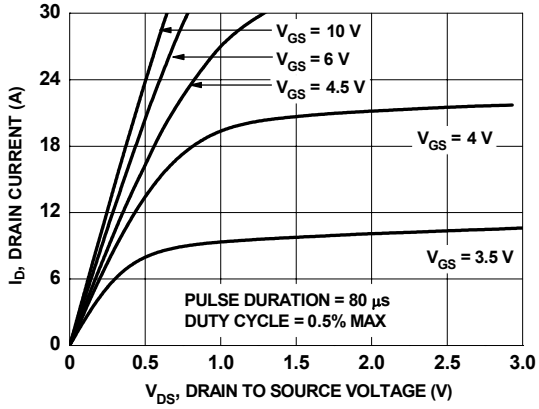


Figure 1. On Region Characteristics

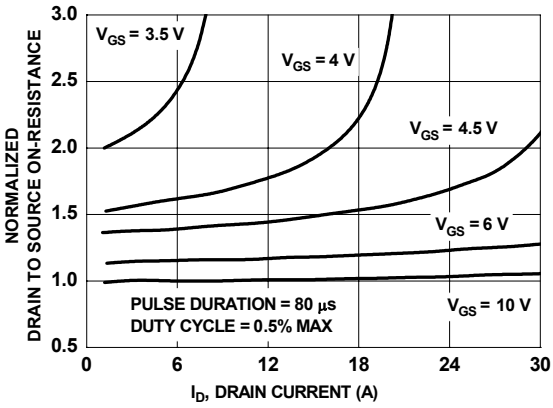


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

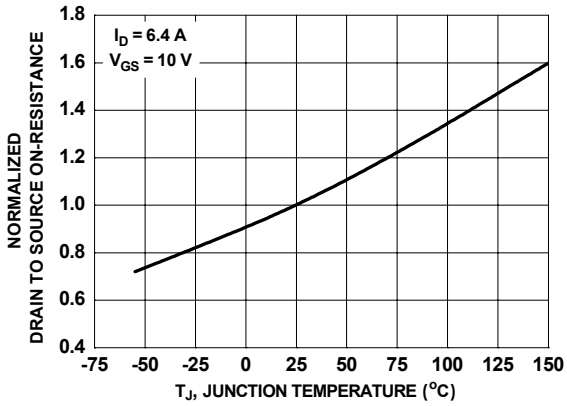


Figure 3. Normalized On Resistance vs Junction Temperature

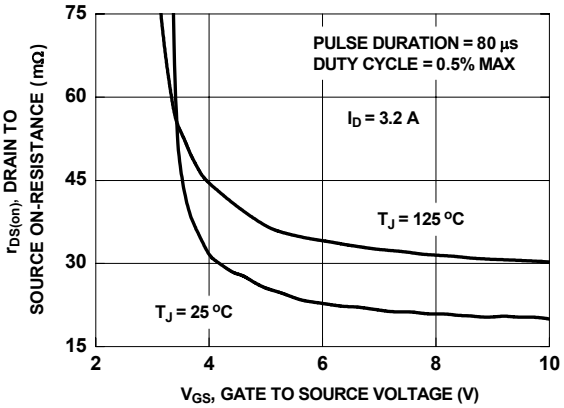


Figure 4. On-Resistance vs Gate to Source Voltage

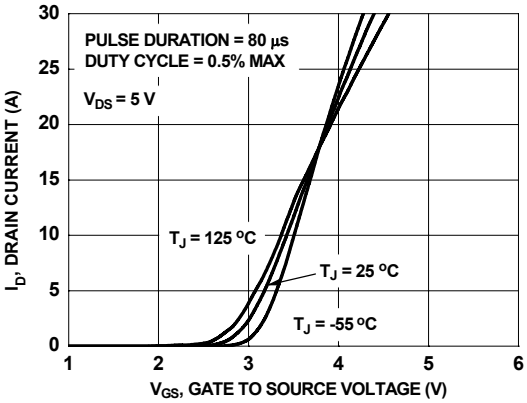


Figure 5. Transfer Characteristics

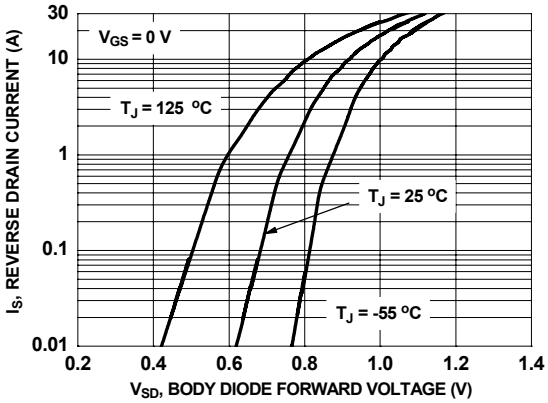


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (Q1 N-Channel) T_J = 25 °C unless otherwise noted

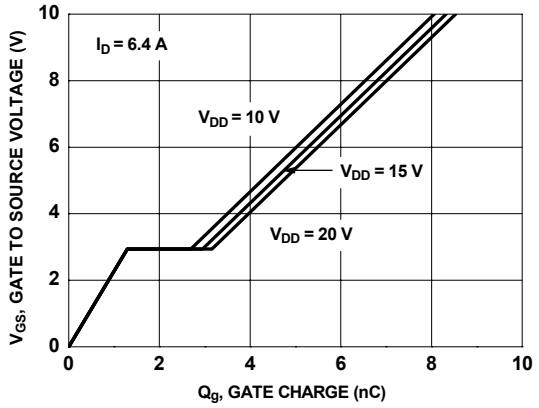


Figure 7. Gate Charge Characteristics

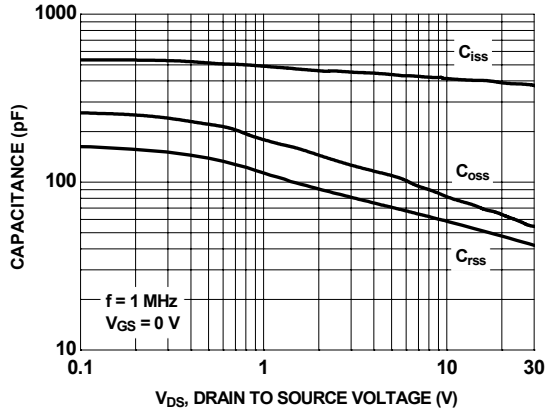


Figure 8. Capacitance vs Drain to Source Voltage

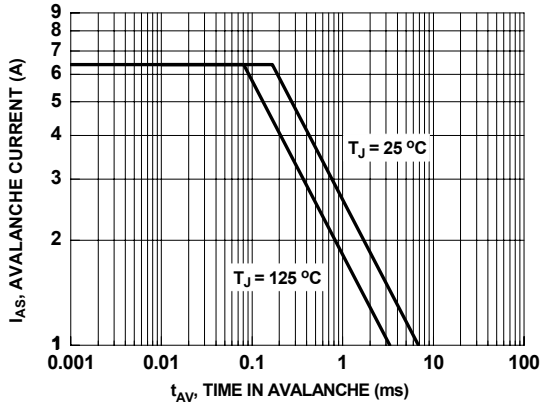


Figure 9. Unclamped Inductive Switching Capability

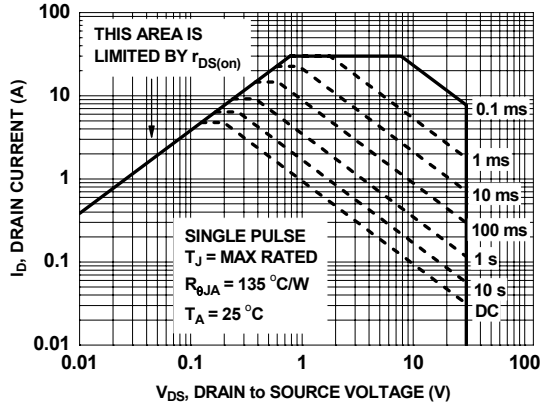


Figure 10. Forward Bias Safe Operating Area

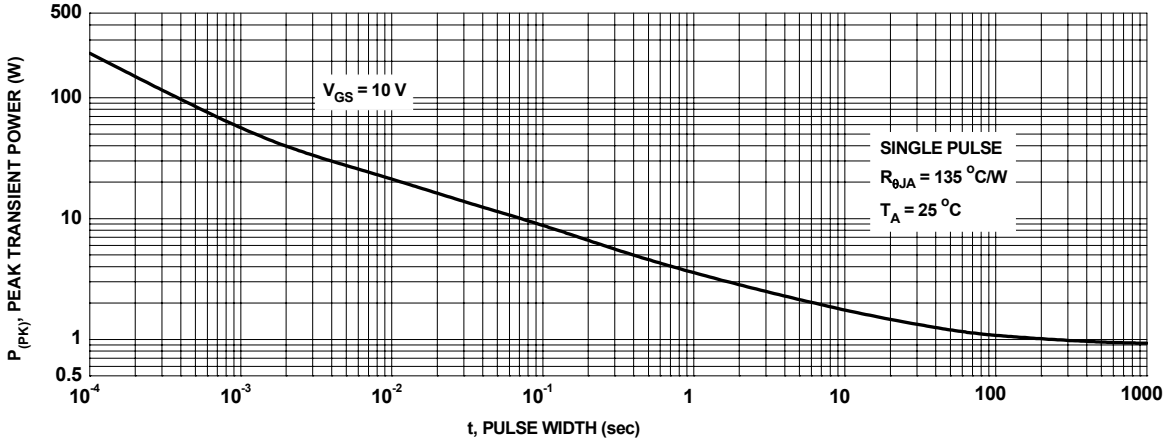


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q1 N-Channel) T_J = 25 °C unless otherwise noted

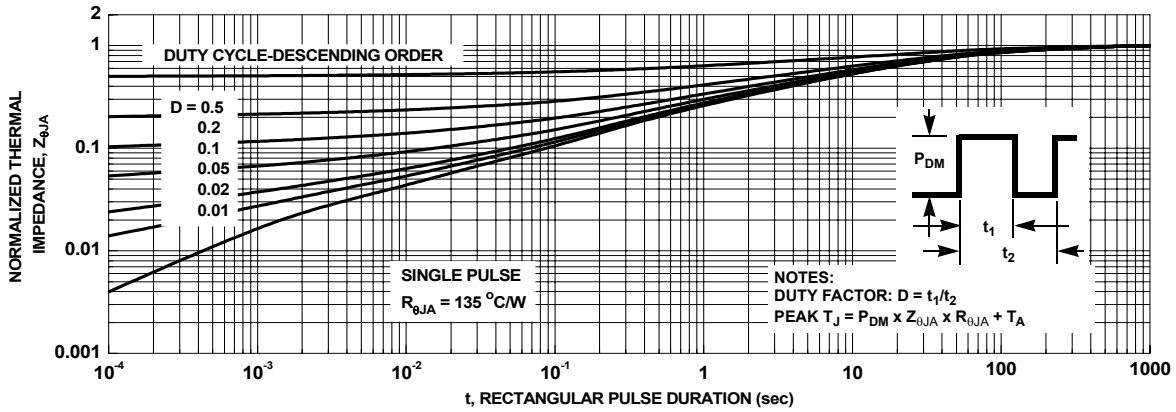


Figure 12. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (Q2 P-Channel) T_J = 25 °C unless otherwise noted

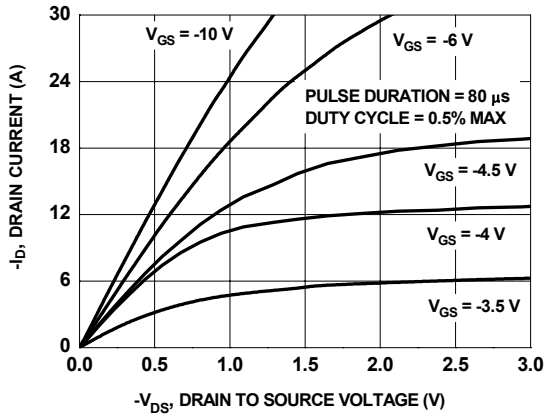


Figure 15. On- Region Characteristics

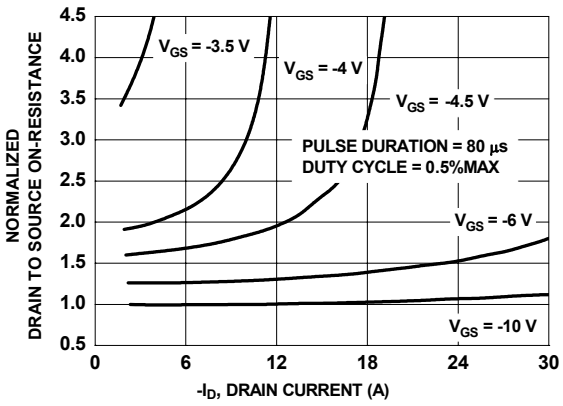


Figure 16. Normalized on-Resistance vs Drain Current and Gate Voltage

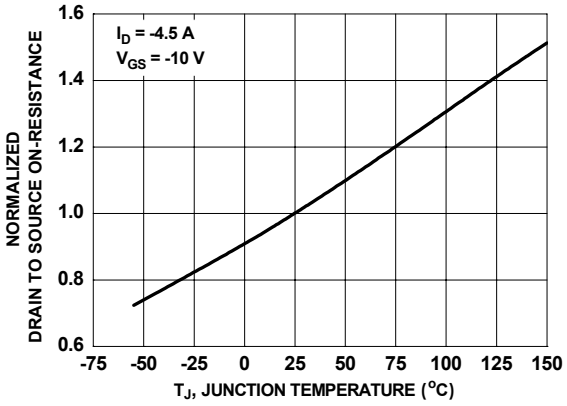


Figure 17. Normalized On-Resistance vs Junction Temperature

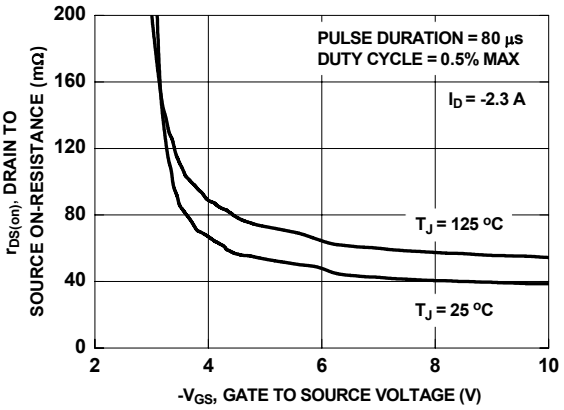


Figure 18. On-Resistance vs Gate to Source Voltage

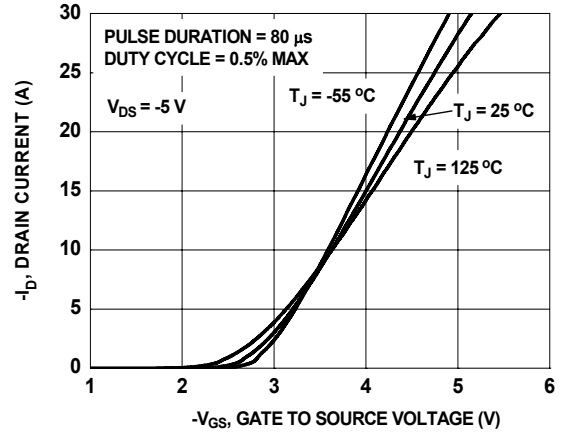


Figure 19. Transfer Characteristics

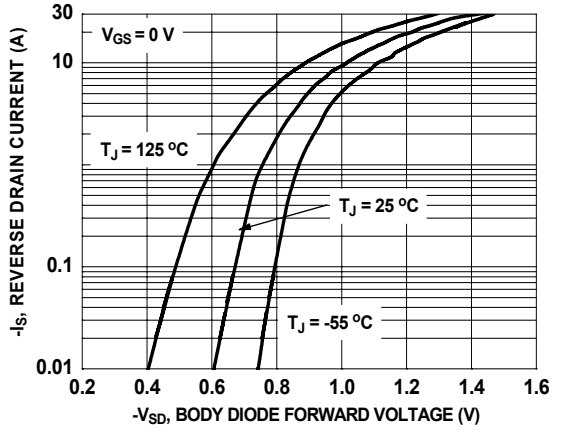


Figure 20. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics (Q2 P-Channel) T_J = 25 °C unless otherwise noted

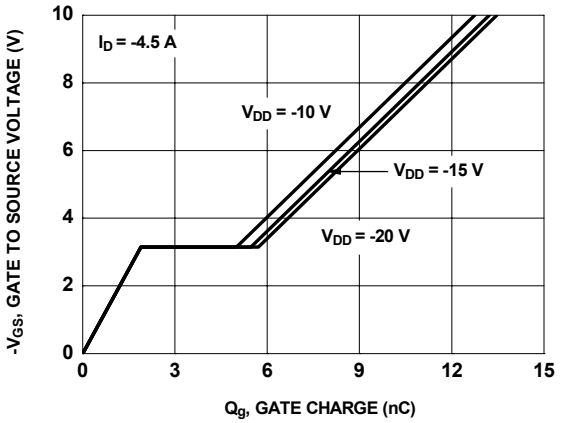


Figure 21. Gate Charge Characteristics

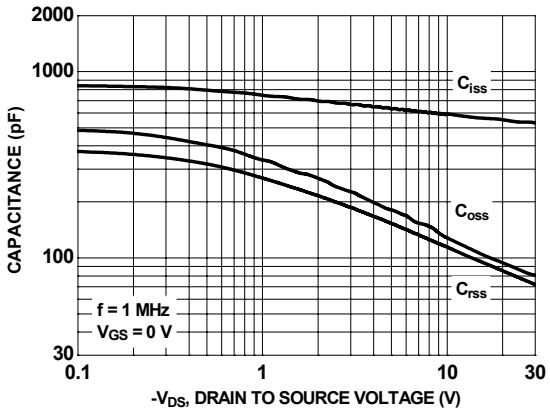


Figure 22. Capacitance vs Drain to Source Voltage

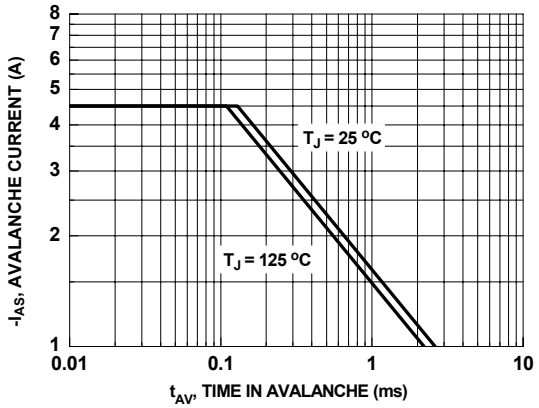


Figure 23. Unclamped Inductive Switching Capability

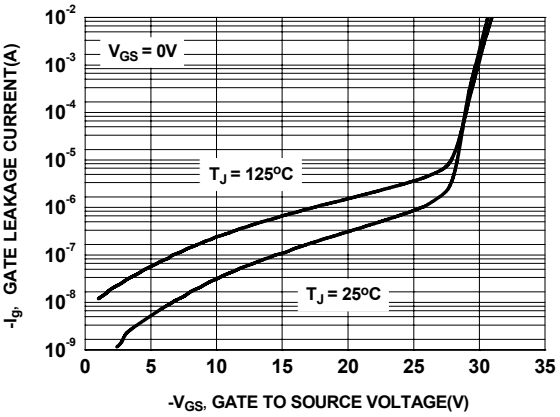


Figure 24. Ig vs Vgs

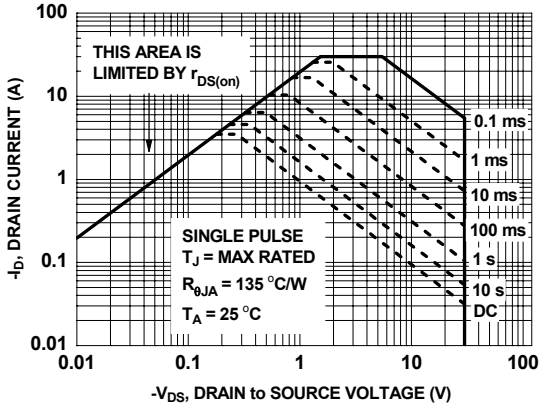


Figure 25. Forward Bias Safe Operating Area

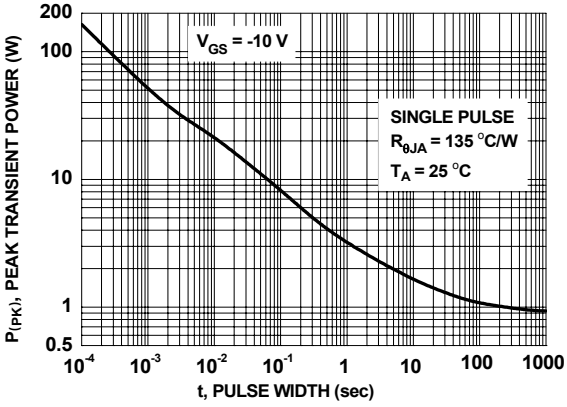


Figure 26. Single Pulse Maximum Power Dissipation

Typical Characteristics (Q2 P-Channel) T_J = 25 °C unless otherwise noted

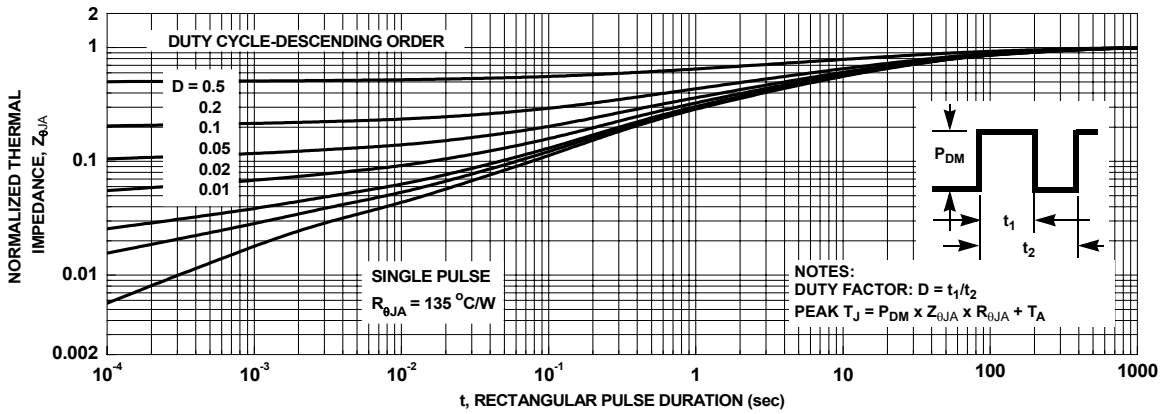


Figure 27. Junction-to-Ambient Transient Thermal Response Curve

Physical Dimensions

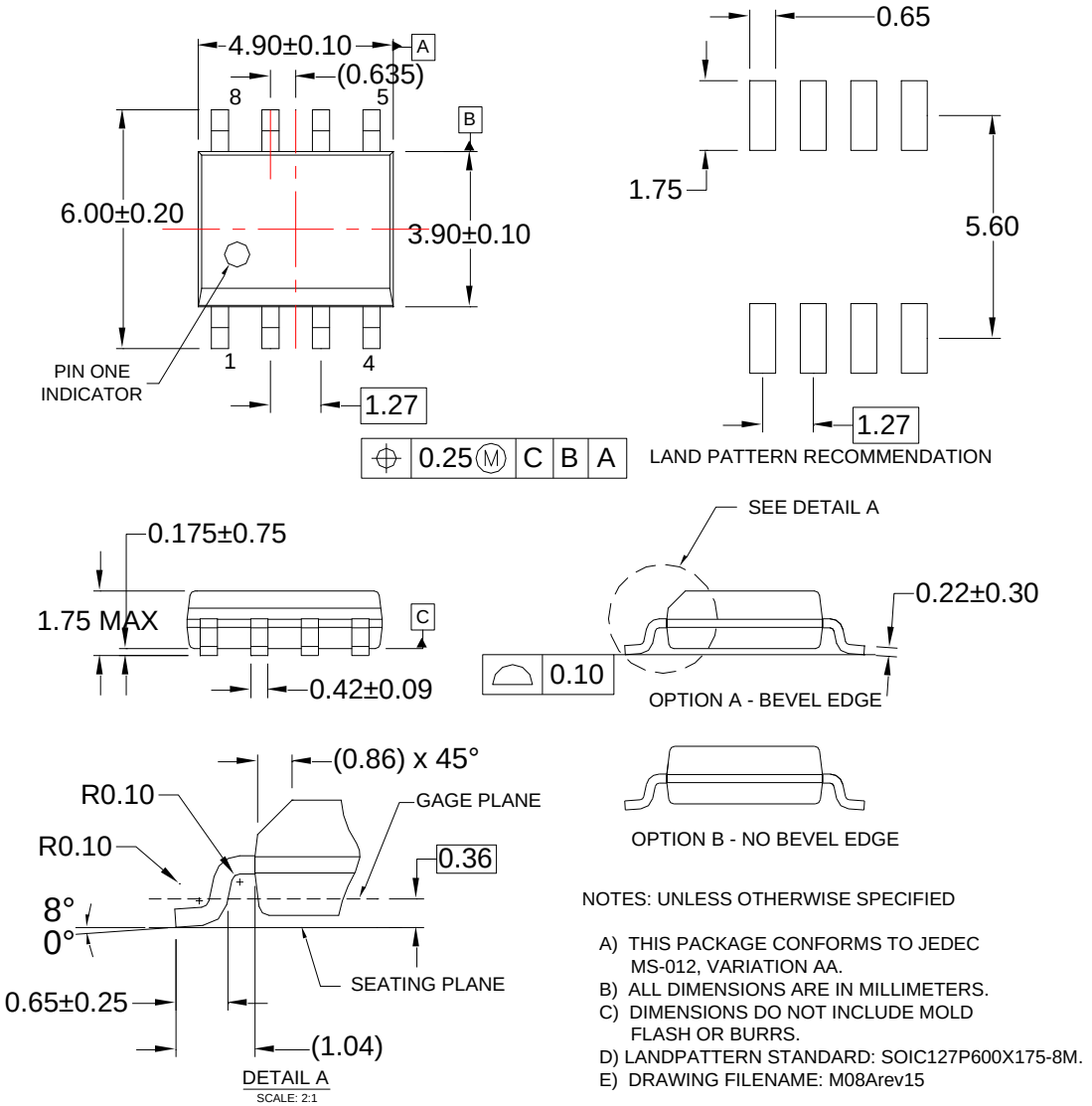


Figure 16. 8-Lead, SOIC,JEDEC MS-012, .150-inch Narrow Body

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